

3113.00

04-17-2000

FLH Ref. No.: 450100-02377

R

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

101322058

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies)

Hideyuki SHIMIZU, Akira HONJO, Yoshihiro YOSHIOKA, Tadayoshi ITANI

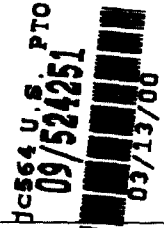
Additional name(s) of conveying party(ies) attached?
☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: SONY CORPORATION
7-35 Kitashinagawa 6-chome
Shinagawa-Ku, Tokyo 100-31, JapanAdditional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment
☐ Security Agreement
☐ Merger
☐ Change of Name
☐ Other

Execution Date: February 18, February 16, February 18 and February 18, 20004. Application number(s) or patent number(s): 09524251If this document is being filed together with a new application, the execution date of the application is: February 18, February 16, February 18 and February 18, 2000

A. Patent Application No.(s) _____ filed _____

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: WILLIAM S. FROMMER

Internal Address: FROMMER LAWRENCE & HAUG LLP

Street Address: 745 FIFTH AVENUE

City: NEW YORK State: N.Y. Zip: 10151

6. Total number of applications and patents involved

17. Total fee (37 CFR 3.41) \$ 40.00
☒ Enclosed
☐ Authorized to be charged to deposit account 50-03208. Deposit account number:
(Attach duplicate copy of this page if paying by deposit account)

Do not use this space

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William S. Frommer

Name of Person Signing

Signature

March 13, 2000

Date

Total number of pages including cover sheet, attachments, and document: 3

04/14/2000 JSH08077 00000280 09524251

01 FC:581

(40.00 DP

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Box Assignments
Washington, D.C. 20231

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

CHARACTER GENERATOR AND CHARACTER GENERATING METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

HIDEYUKI SHIMIZU

Name of first or sole inventor

Feb. 18, 2000
Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of first or sole inventor

Hideyuki Shimizu

Feb. 18, 2000

Signature of first or sole inventor

Date of this assignment

AKIRA HONJO

Name of second inventor

Feb. 16, 2000
Execution date of U.S. Patent Application

TOKYO, JAPAN

Residence of second inventor

Akira Honjo

Feb. 16, 2000

Signature of second inventor

Date of this assignment

YOSHIHIRO YOSHIOKA

Name of third inventor

Feb. 18, 2000
Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of third inventor

Yoshihiro Yoshioka

Feb. 18, 2000

Signature of third inventor

Date of this assignment

ADDITIONAL INVENTOR(S) ON NEXT PAGE

PATENT

REEL: 010688 FRAME: 0836

TADAYOSHI ITANI

Feb. 18, 2000

Name of fourth inventor

Execution date of U.S. Patent Application

KANAGAWA, JAPAN

Residence of fourth inventor

Tadayoshi Itani

Feb. 18, 2000

Signature of fourth inventor

Date of this assignment

Name of fifth inventor

Execution date of U.S. Patent Application

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Name of sixth inventor

Execution date of U.S. Patent Application

Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

Residence of seventh inventor

Signature of seventh inventor

Date of this assignment

Name of eighth inventor

Execution date of U.S. Patent Application

Residence of eighth inventor

Signature of eighth inventor

Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment